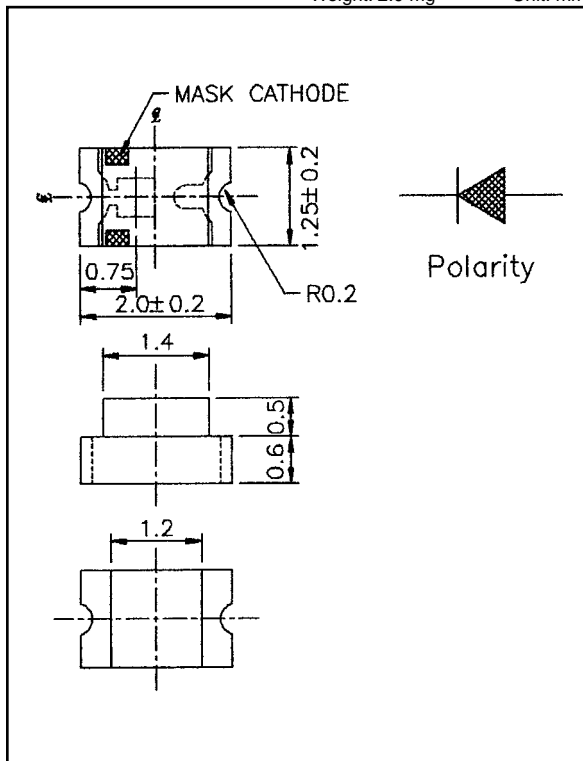




Weight: 2.0 mg

Unit: mm



## AND4BB

### InGaN Ultra Bright Blue Light Emission Surface Mount Package

#### Features

- Small package size (8mm tape on 7" diameter reel)
- Compatible with automatic placement equipment
- 2.0 (l) x 1.25 (w) x 1.1 (h) size
- Compatible with infrared & vapor phase reflow solder process
- Mono-color type

#### Maximum Ratings (T<sub>a</sub> = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	30	mA
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation	P <sub>D</sub>	120	mW
Operating Temperature Range	T <sub>opr</sub>	-20 to 80	°C
Storage Temperature Range	T <sub>Stg</sub>	-30 to 100	°C

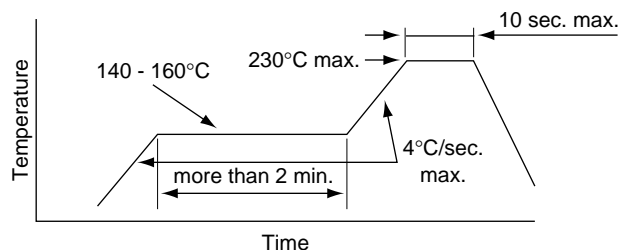
#### Electro-Optical Characteristics (T<sub>a</sub> = 25°C)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	—	3.5	4.0	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V	—	—	10	μA
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20 mA	10	19	—	mcd
Peak Emission Wavelength	I <sub>P</sub>	I <sub>F</sub> = 20 mA	—	468	—	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20 mA	—	40	—	nm
Dominant Wavelength	λ <sub>d</sub>	I <sub>F</sub> = 20 mA	—	470	—	nm
Full Viewing Angle	2θ 1/2	I <sub>V</sub> = 1/2 Peak	—	140	—	degree

#### Precaution

Please be careful of the following:

1. Manual soldering: maximum temperature of iron tip: 260°C max.  
Soldering time: within 5 sec. per solder-land  
Soldering portion of lead: up to 1.6 mm from the body of the device
2. Reflow solder: recommended condition is as follows:



For reflow soldering

